MOSFET – Power, Single P-Channel

-60 V, -100 A, 7.7 $m\Omega$

Features

noted) (Notes 1, 2, 3)

Symbol

V_{DSS}

V_{GS}

 I_D

 P_D

In

 P_{D}

 I_{DP}

T_J, T_{STG}

ls

E_{AS}

 T_{L}

- Small Footprint (5 x 6 mm) for Compact Design
- Low R_{DS(on)} to Minimize Conduction Losses
- NVMFS5A160PLZWF: Wettable Flank Option for Enhanced Optical Inspection

SPECIFICATION MAXIMUM RATINGS (T_J = 25°C unless otherwise

Steady

Steady State

Operating Junction and Storage Temperature

Single Pulse Drain to Source Avalanche En-

Lead Temperature for Soldering Purposes

Stresses exceeding those listed in the Maximum Ratings table may damage the

device. If any of these limits are exceeded, device functionality should not be

Source Current (Body Diode)

 $ergy (L= 1.0 \text{ mH}, I_{L(pk)} = -26 \text{ A})$

assumed, damage may occur and reliability may be affected.

(1/8" from case for 10 s)

PW \leq 10 μ s,

duty cycle $\leq 1\%$

State

Parameter

• AEC-Q101 Qualified and PPAP Capable

Drain to Source Voltage

Gate to Source Voltage

Continuous Drain,

Power Dissipation

Current R_{0.IC},

R_{0JC} (Note 1)

Current $R_{\theta JA}$ (Notes 1, 2, 3)

Power Dissipation

R_{0JA} (Note 1, 2)

Pulsed Drain

Current

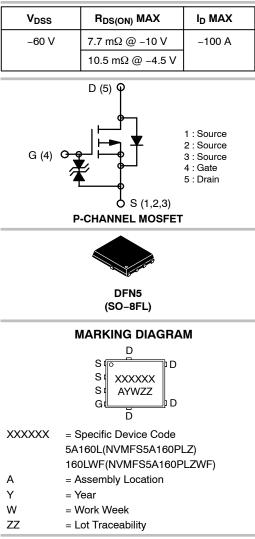
(Notes 1, 3)

• These Devices are Pb-Free and are RoHS Compliant



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ORDERING INFORMATION See detailed ordering and shipping information on page 7 of

this data sheet.

THERMAL CHARACTERISTICS

Symbol	Parameter		Unit
$R_{\theta JC}$	Junction to Case Steady State	0.75	0 0 AN
$R_{\theta JA}$	Junction to Ambient Steady State (Note 3)	39	°C/W

Value

-60

±20

-100

200

-15

3.8

-400

–55 to

+175

-100

335

260

 $T_C = 25^{\circ}C$

 $T_{\rm C} = 25^{\circ}{\rm C}$

T_A = 25°C

 $T_A = 25^{\circ}C$

Unit

V

V

А

W

Α

W

А

°C

А

mJ

°C

1. The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.

2. Surface mounted on FR4 board using a 650 mm², 2 oz. Cu pad.

3. Maximum current for pulses as long as 1 second is higher but is dependent on pulse duration and duty cycle.

ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}C$ unless otherwise noted)

Symbol	Parameter	Test Condition		Min	Тур	Max	Unit
OFF CHARA	CTERISTICS						
V _{(BR)DSS}	Drain to Source Breakdown Volt- age	I _D = -1 mA, V _{GS} = 0 V		-60			V
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -60 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$	$T_J = 25^{\circ}C$			-1.0	μA
			T _J = 100°C (Note 4)			-100	μΑ
I _{GSS}	Gate to Source Leakage Current	V_{GS} = ±16 V, V_{DS} = 0 V				±10	μA

ON CHARACTERISTICS (Note 5)

V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = -10 \text{ V}, \text{ I}_{D} = -1 \text{ mA}$		-1.2		-2.6	V
R _{DS(on)}	Drain to Source On Resistance	V _{GS} = -10 V	I _D = -50 A		5.8	7.7	
		V _{GS} = -4.5 V	I _D = -50 A		7.3	10.5	mΩ
9 _{FS}	Forward Transconductance	V _{DS} = -10 V, I _D = -50 A			119		S

CHARGES, CAPACITANCES & GATE RESISTANCE

C _{iss}	Input Capacitance	V _{GS} = 0 V, f = 1 MHz		7700	
C _{oss}	Output Capacitance	V _{DS} = -20 V,		720	pF
C _{rss}	Reverse Transfer Capacitance			540	
Q _{g(tot)}	Total Gate Charge	V _{GS} = -10 V, I _D = -50 A		160	
Q _{gs}	Gate to Source Charge	V _{DS} = -36 V,		24	nC
Q _{gd}	Gate to Drain Charge			45	

SWITCHING CHARACTERISTICS (Note 6)

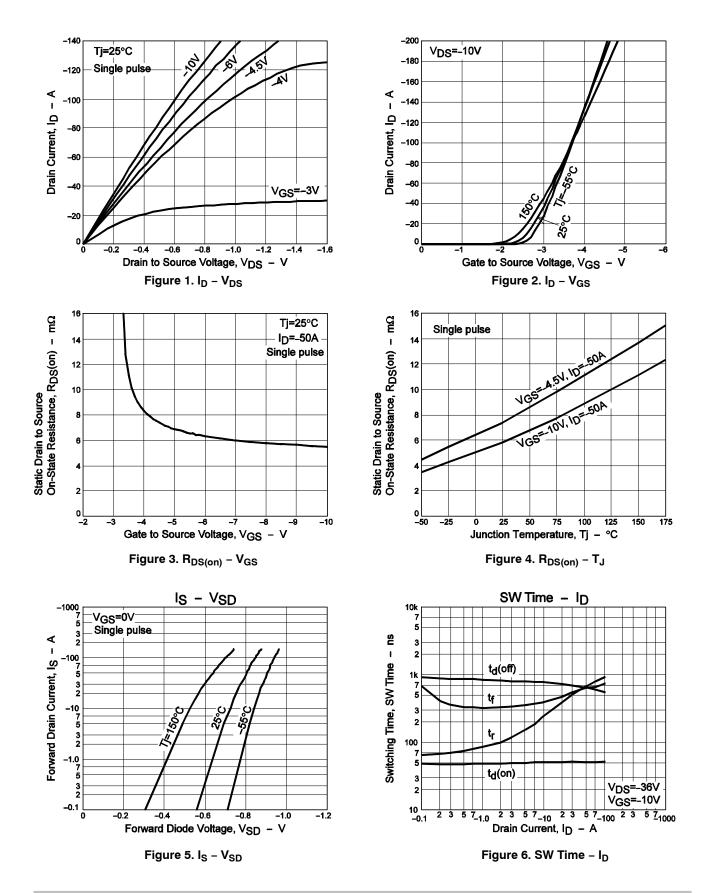
t _{d(on)}	Turn-On Delay Time	$V_{DS} = -36 \text{ V}, \text{ I}_{D} = -50 \text{ A},$		50	
t _r	Rise Time	$V_{GS} = -10 V,$ $R_G = 50 \Omega$		690	
t _{d(off)}	Turn-Off Delay Time			645	ns
t _f	Fall Time			643	

DRAIN-SOURCE DIODE CHARACTERISTICS

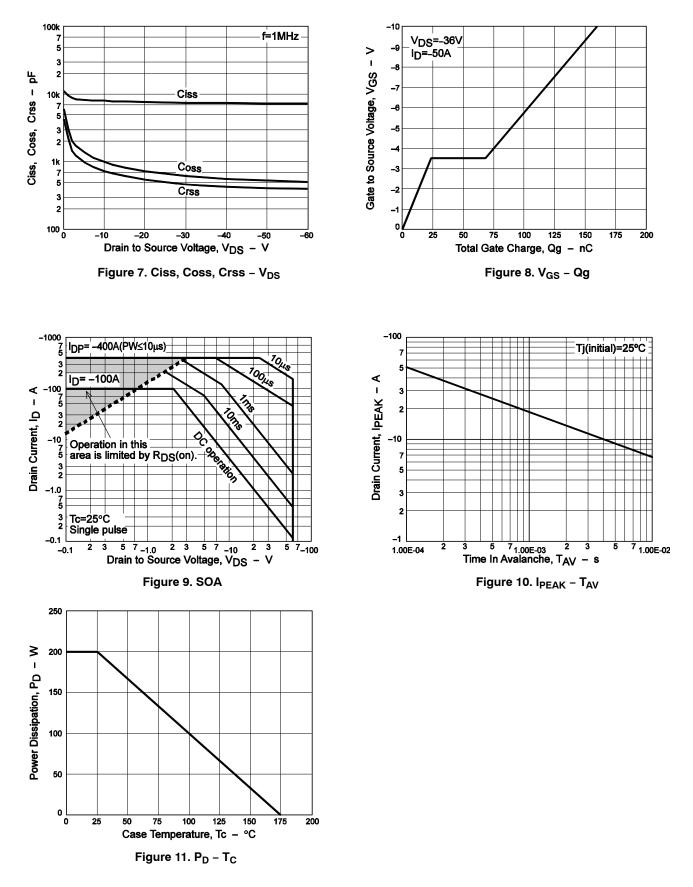
V _{SD}	Forward Diode Voltage	$V_{GS} = 0 V, I_{S} = -50 A$		-0.83	-1.5	V
t _{rr}	Reverse Recovery Time	$V_{GS} = 0 V, I_{S} = -50 A$		93		ns
Q _{rr}	Reverse Recovery Charge	di/dt = 100 A/µs		218		nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 4. The maximum value is specified by design at $T_J = 100$ °C. Product is not tested to this condition in production. 5. Pulse Test: pulse width $\leq 300\mu$ s, duty cycle $\leq 2\%$. 6. Switching characteristics are independent of operating junction temperatures.

TYPICAL CHARACTERISTICS



TYPICAL CHARACTERISTICS



TYPICAL CHARACTERISTICS

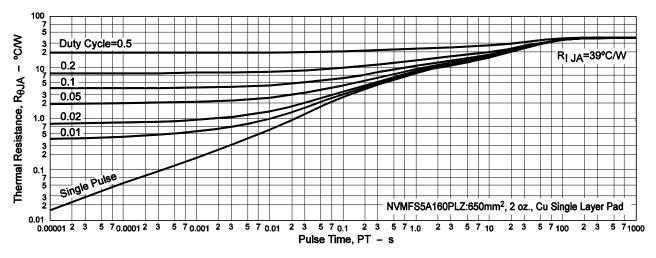
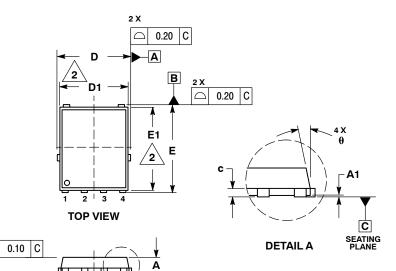


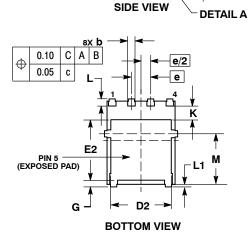
Figure 12. $R_{\theta JA}$ – Pulse Time

DFN5 5x6, 1.27P (SO-8FL) CASE 488AA **ISSUE M**



NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION DI AND E1 DO NOT INCLUDE MOLD FLASH PROTRUSIONS OR GATE BURRS.

	MILLIMETERS					
DIM	MIN	NOM	MAX			
Α	0.90	1.00	1.10			
A1	0.00		0.05			
b	0.33	0.41	0.51			
С	0.23	0.28	0.33			
D	5.00	5.15	5.30			
D1	4.70	4.90	5.10			
D2	3.80	4.00	4.20			
E	6.00	6.15	6.30			
E1	5.70	5.90	6.10			
E2	3.45	3.65	3.85			
е		1.27 BSC				
G	0.51	0.575	0.71			
к	1.20	1.35	1.50			
L	0.51	0.575	0.71			
L1	(0.125 REF	-			
М	3.00	3.40	3.80			
θ	0 °		12 °			



STYLE 1: PIN 1. SOURCE 2. SOURCE 3. SOURCE 4. GATE 5. DRAIN

//

 \square

0.10 C

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ORDERING INFORMATION

Device	Marking	Package	Shipping (Qty / Packing) [†]
NVMFS5A160PLZT1G	5A160L	DFN5 5x6, 1.27P (SO-8FL) (Pb-Free)	1.500 / Tape & Reel
NVMFS5A160PLZWFT1G	160LWF	DFN5 5x6, 1.27P (SO-8FL) (Pb-Free, Wettable Flanks)	1.500 / Tape & Reel
NVMFS5A160PLZT3G	5A160L	DFN5 5x6, 1.27P (SO-8FL) (Pb-Free)	5.000 / Tape & Reel
NVMFS5A160PLZWFT3G	160LWF	DFN5 5x6, 1.27P (SO-8FL) (Pb-Free, Wettable Flanks)	5.000 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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